PRODUCT ADVANTAGE

Eliminate cleaning process for ball bumping

Enhances solder joint strength 5-10X

Eliminates underfill

Excellent process compatibility

High reliability

100% reworkable

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

YINCAE Advanced Materials, LLC
19 Walker Way
Albany, NY 12205 USA
(518) 452-2880
www.yincae.com

Worldwide Service and Sales Organization
info@yincae.com

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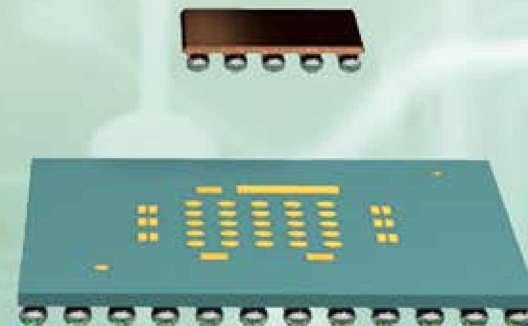
INNOVATION AT ITS BEST



BP 256 BALL ATTACH ADHESIVE OVERVIEW

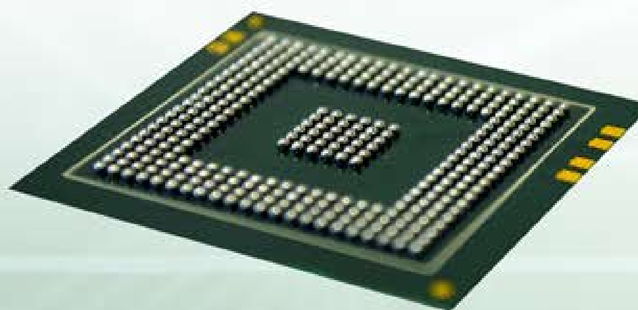
Preferred by global leaders in the electronics manufacturing industry

YINCAE® BP 256 Ball Attach Adhesives

Solder Joint Encapsulants

Process flow for BP 256

1. Apply BP 256 onto pads
2. Place solder balls
3. Send through reflow

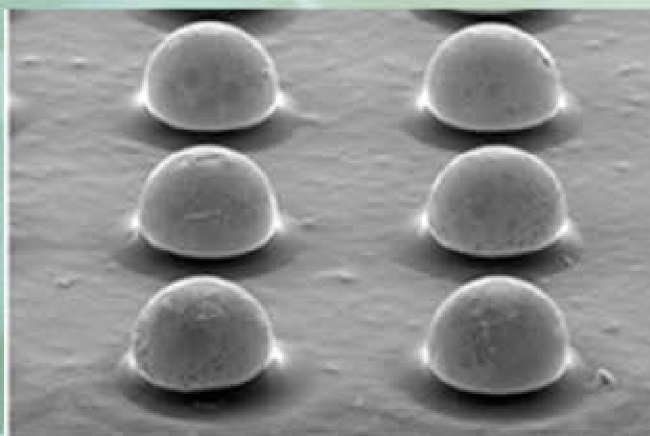


Ball Attachment

The YINCAE® BP 256 products are a series of lead-free (SAC alloys) ball bumping adhesives that are designed to enhance solder joint reliability and eliminate cleaning processes for ball bumping procedures on CSP, BGA, flip chip, and PoP applications.

BP 256 is designed to eliminate underfilling processes during SMT assembly and thus reduces cost and increases throughput.

BP 256 has demonstrated excellent drop and thermal cycling performance as well as a high and consistent shear strength.



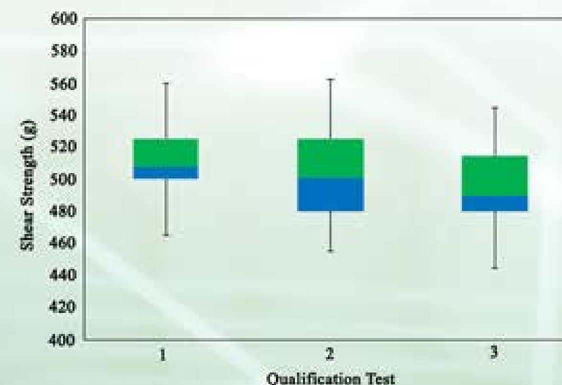
SEM image of solder balls bumped with BP 256

Availability

BP 256 - R
Red, used for printing applications

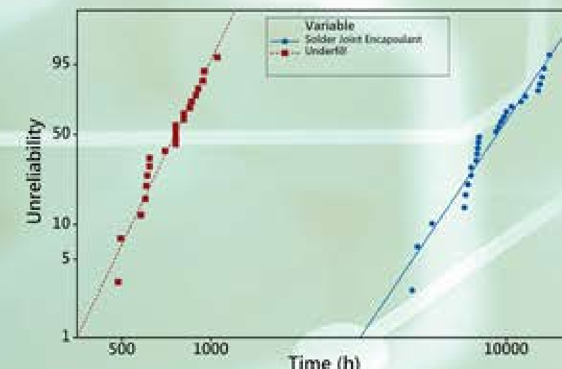
BP 256 - B
Black, used for printing applications

BP 256 - T
Clear, used for pin transfer applications



The shear strength of BP 256 remains consistent

*based on the average of over 3000 components



BP 256 enhances thermocycling 10x more than tacky flux. (Thermal Cycling Conditions: SAC305; I/O 1156; -55°C~150°C; 1h/cycle.)

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.